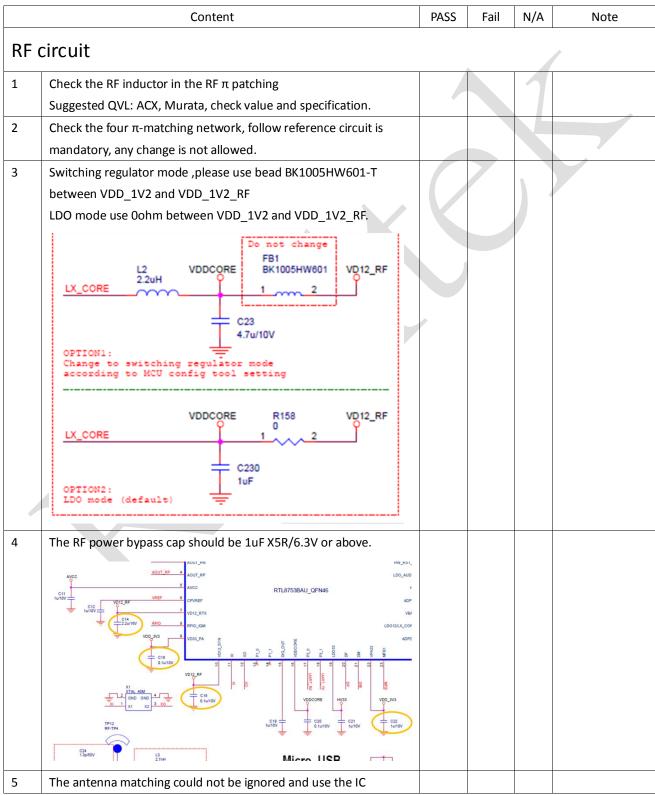


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## RTL8753BAU Schematic check list v1.1

Project:	Schematic Version:	Customer:
Review by:	Approval by:	Date:



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	matching to replace it, e.g. in the RF circuit, at least 4 IC matching				
	and 3 antenna matching is required.				
Analog and Digital Circuit					
Allo	nog and Digital Circuit				
6	The capacitor 4.7uF at the HV pin(28 pin) should be X5R/10V or				
	above.				
	LDO AUX 31				
	30 HW RST N				
	HW_RST_N VDD_1V8				
	LDO_AUDIO 29				
	$\frac{28}{4.7}$ $\frac{\text{HV}}{4.7}$ $\frac{\text{C10}}{1}$ $\frac{\text{C22}}{1}$				
	ADPIN 27 = =				
	VBAT 26 VDD_VBAT				
	25 IX CORE				
	LDO12/LX_CORE C15				
7	Use SWR power inductor should be 2.2uH, capacitor 4.7uF				
	The inductor spec: saturation current> 0.5A, DCR as small as				
	possible.				
	Note: very important, saturation current is not equal to rated				
	current.				
	The capacitor spec: X5R/6.3V or above				
	Inductor suggested QVL: Zenithtek, TAIYO				
	Capacitor suggested QVL: Walsin, Murata, Darfon,				
	ZRB15XR61A475ME01D/MURATA				
9	40MHz crystal spec				
	(a) Tolerance under room temperature: ±5ppm				
	(b) Temperature variation: ±15ppm under -40°C~85°C				
	→ (a)+(b) total variation ±20ppm				
	Or total variation: ±20ppm with customer defined working				
	temperature				
	If $C_L=7pF \rightarrow ESR$ could not be over $50\Omega$				
	If $C_L=9pF \rightarrow ESR$ could not be over $40\Omega$				
	If customer does not do frequency calibration in mass production,				
	it is suggested to switch off the internal trimming cap, customer				
	should fine tune the external load capacitor and use high precision				
	crystal part, e.g. crystal with ±5ppm spec				
10	32.768K crystal spec				
	If C <sub>L</sub> = 7pF, the external load capacitor could be ignored, otherwise,				
	the external load capacitor is required.				
11	HW_RST:				

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	There should be a '0.1uF' capacitor between this pin and ground.
	An external adapter in reset circuit is suggested to reserve.
12	The capacitor at 3.3V power should be 1uF/10V/X5R or above.
	The capacitor at 1.8/1.2V power should be X5R/6.3V or above.
13	The capacitor at LDO_AUX should be 1uF/X5R/6.3V or above
14	A 1uF/X5R capacitor at CPV <sub>REF</sub> is required in the internal codec is
	enabled.
15	Battery thermal protection, the NTC thermistor should be attached
	on the battery pack, do not reserve it on EVB, there is no
	relationship between the battery temperature and PCB
	temperature. For this purpose, at least three pin on the battery
	connector is required, VBAT, GND and THE_DET.
16	If a bead at the power path RTL8773/8753 VBAT is needed, the
	bead DCR should be smaller than $0.5\Omega$
17	The external SPI flash QVL: MXIC, ESMT and GD, the others is not
	supported.
18	The mic phone / line-in is used for voice, the value of ac couple
	capacitor is the 1uF
	1
	MAIN MIC for PHONE  C68 L23 U8 SPH1611LR5H-1 MIC_BIAS
	C68 L23 SPH1611LRSH-1 MIC_BIAS 1UF BEAD BLM15BD221 MIC1_P
	C206 1uF BEAD BLM15BD222 4 4
	MIC1_N C71
	3 GND =
	<del>-</del> <del>- 2.888.3</del> <del>-</del>
	Audio Jack <sup>1</sup>
	Audio Jack
	BLM15BD221SN1D P2
	AUX_L 1
	AUX_R 1 2 30 40
	FB3 BLM15BD221SN1D
	%/Murata OPTIONAL N PJ2503B
	2 R1 70K1% SR2 2K/1%
	<u></u>
	AUX_DET
20	The placement and layout should be the differential mode even
	the single-end mic phone

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22 Always check if there is any new updated reference from REALTEK.

## **MISC**

23 Check the pin definition and symbol is correct.

24 Check the MP test point

Mandatory test point for control:

UART\_RX, UART\_TX, P2\_0, VBAT, ADP\_IN, GND

PMU test point:

Mandatory: switching regulator output (AVCC\_DRV and VDDCORE), VPA33

Optional: DIG\_OUT, AVCC, MIC\_BIAS

RF test point:

- Add a RF test point after the IC RF matching network

Audio test point:

DAC: AOUT\_LP/LN/RP/RN

- ADC: MIC1/2

PASS: the design is correct  $\circ$ 

FAIL: Not properly, need to describe the reason.

N/A: No such request